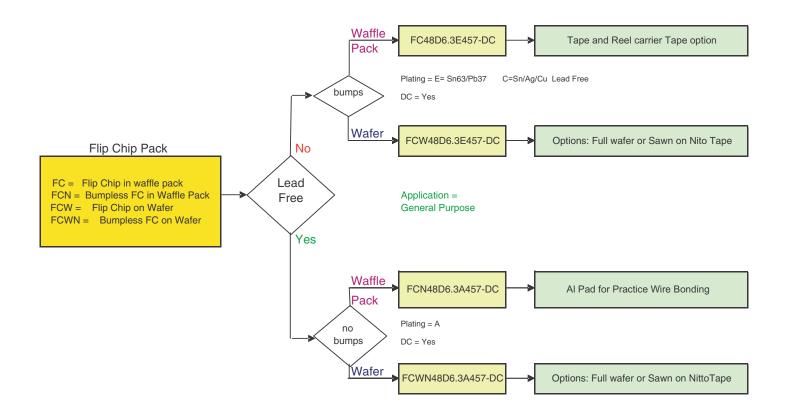


Flip Chip

| FC SERIES FC = Flip Chip (standa FCN = Bumpless Die FCW = Bump Wafer FCWN = Bumpless Wa | BUMPS | D | 5.08 DIE SIZE millimeter (mm) | E | 457 - DC Bump Pitch micron (μm) |
|---|---|---|---------------------------------|---|--|
| | Bump Size $C = 165 \mu m$ $D = 190 \mu m$ $G = 135 \mu m$ $H = 105 \mu m$ | | | BUMP COMPOSITION E = Eutectic 63/37 A = Al Pad (bumpless) S = Gold Stud Bump C = Sn/Ag/Cu | |
| | | | | NTR : | OPTION Daisy Chain = Sawn on Tape with ring = Tape & Reel |



Selecting FC



Suffix Codes:

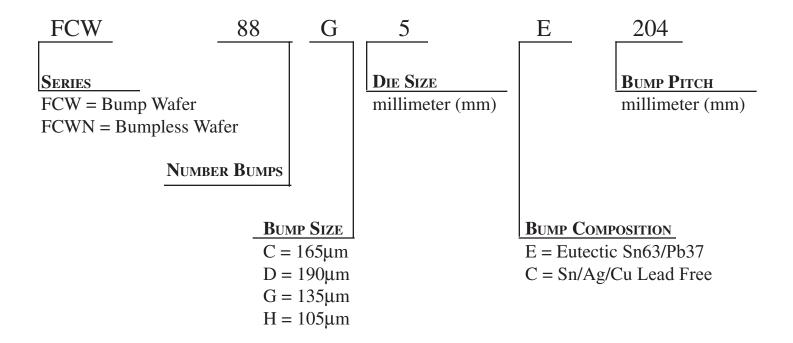
"DC" = Daisy Chain (See Drawing for Details)

Plating: "E" = Sn63/Pb37, S = Gold Stud Bump C = 95.5Sn/3.5Ag/1.0Cu

Pack: Normally in 2" Square Waffle Packs

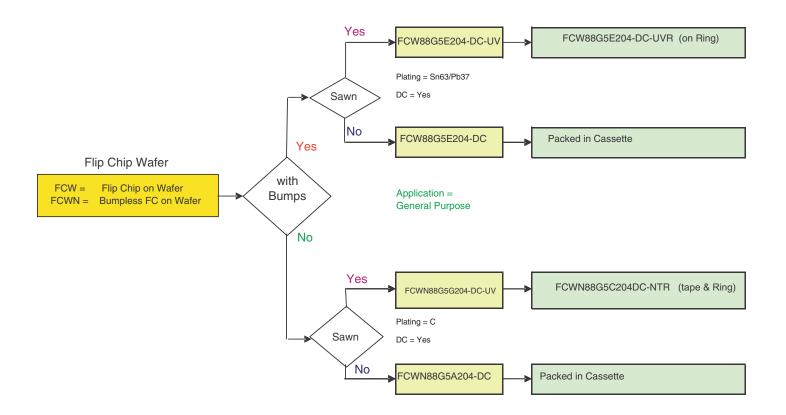


Flip Chip on Wafers





Selecting Flip Chip Wafers



Suffix Codes:

"DC" = Daisy Chain (See Drawing for Details) "ISO"= Isoloated connections

Plating: "E" = Sn63/Pb37, A = Al Pad C = 95.5Sn/3.5Ag/1.0Cu

Pack: Normally in 2" Square Waffle Packs



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